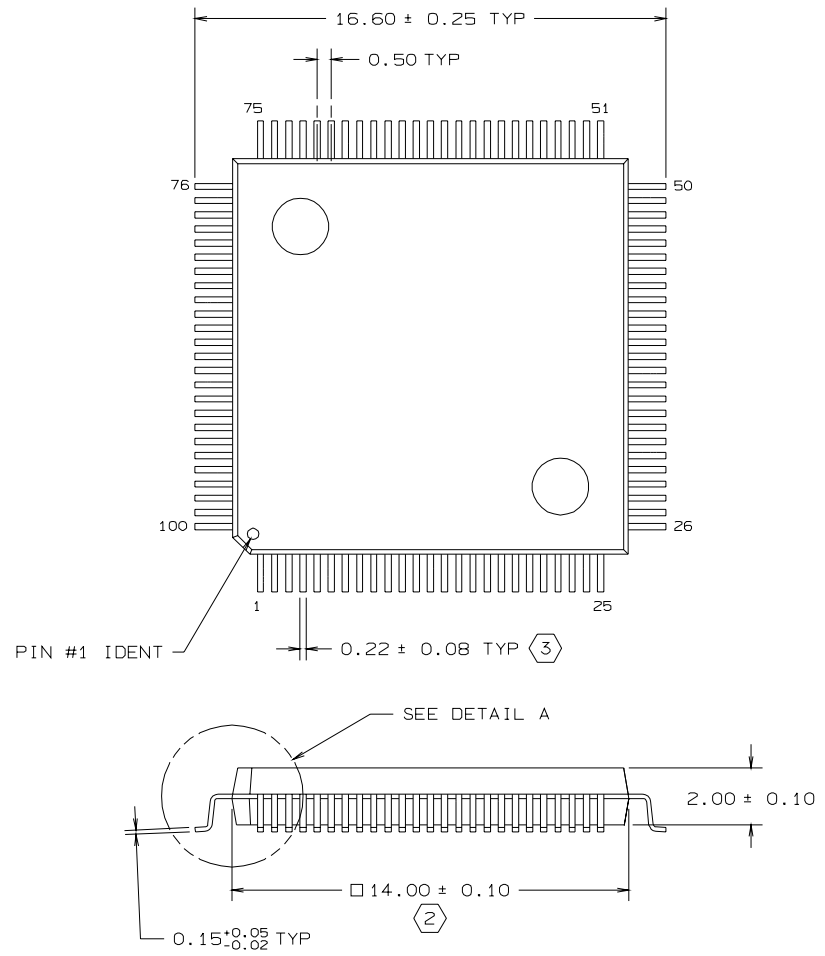


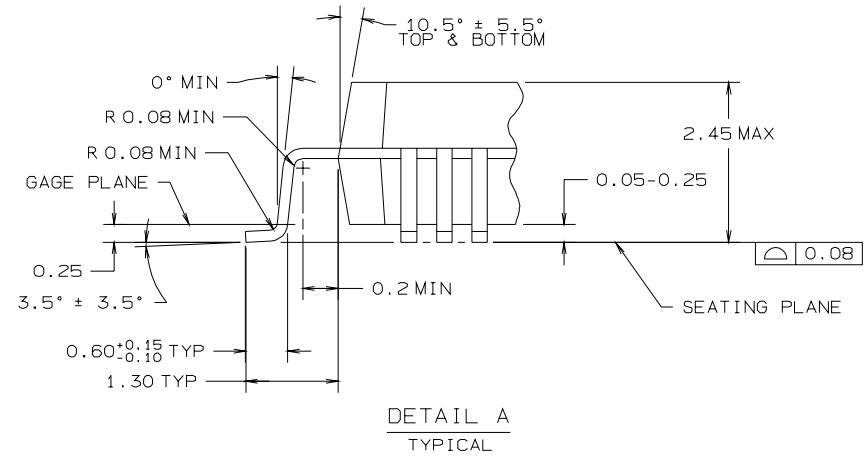
R E V I S I O N S				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	0925B	08/03/92	MS/HJK
B	ADD OPT CORNER;REVISE NOTES.	09733	04/30/93	DEG/HJK
C	REVISE TITLE & DET A;ROTATE 90°.	10157	12/01/93	DEG/



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
5.08 MICROMETERS MINIMUM SOLDER PLATING (85/15)
THICKNESS ON COPPER/ALLOY 42.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25 mm PER SIDE.
- DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION.
ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.15 mm.
- CHAMFERED PACKAGE DOES NOT HAVE EJECTOR PIN MARKS.
- REFERENCE JEDEC METRIC REGISTRATION MO-143,VARIATION CA,
DATED 3/93.



DETAIL A
TYPICAL

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION		
DRAWN MARTA SUCHY	08/03/92	2900 Semiconductor Drive, Santa Clara, CA 95052-8090		
DFGTG. CHK.		PQFP, JEDEC METRIC, (S), 14 X 14 X 2.0mm, 100 LEAD		
ENGR. CHK.				
APPROVAL				
PROJECTION		SCALE	SIZE	DRAWING NUMBER
		N/A	C	MKT-VJU100A
		DO NOT SCALE DRAWING	SHEET	1 OF 1